LN877RPX

Round Type

\$\phi 3.0 mm Series

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	90	mW	
Forward current	I_{F}	30	mA	
Pulse forward current *	I_{FP}	150	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

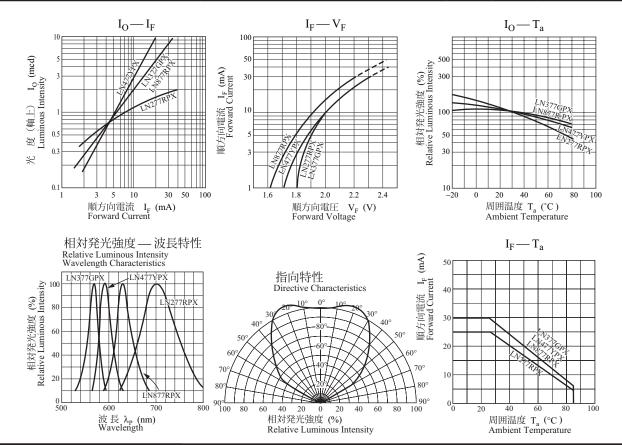
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color / Lens Color

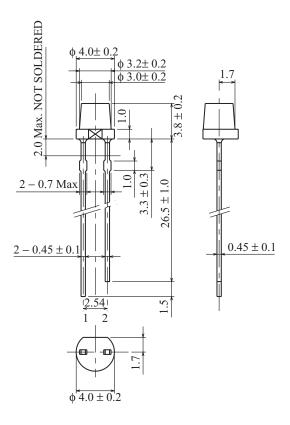
• Orange / Red Diffused

■ Electro-Optical Characteristics $T_a = 25$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		2.0	5.0		mcd
Forward current	I_{F}			20		mA
Forward voltage	V _F	$I_F = 20 \text{ mA}$		2.1	2.8	V
Peak emission wavelength	λ_{P}	$I_F = 20 \text{ mA}$		630		nm
Spectral half band width	Δλ	$I_F = 20 \text{ mA}$		40		nm
Reverse current	I_R	$V_R = 3 V$			10	μΑ



■ Package (Unit: mm)



- Pin name
 - 1: Anode
 - 2: Cathode

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